



Docket No.: SON-1908/DIV  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:  
Takeshi Nogami et al.

Application No.: 10/759,194

Confirmation No.: 7751

Filed: January 20, 2004

Art Unit: 2823

For: METHOD FOR PRODUCING  
SEMICONDUCTOR DEVICE, POLISHING  
APPARATUS, AND POLISHING METHOD

Examiner: F. L. Toledo

**REQUEST FOR PANEL REVIEW**

MS AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

This is in full and timely response to the Office Action mailed on January 9, 2006.  
Reexamination in light of the following remarks is respectfully requested.

**Claims 19, 31** - U.S. Patent No. 5,911,619 to Uzoh et al. (Uzoh) arguably teaches a polishing pad 64, and a platen 62 and a rotatable shaft 68 (Uzoh at Figure 7). Uzoh arguably teaches a rotatable workpiece carrier 66 for holding a wafer W (Uzoh at Figure 7). Uzoh arguably teaches a container 70 coupled to a conduit 72 arranged and dimensioned for dispensing an electrolytic polishing slurry 74 onto the pad 64 during a normal operation of the apparatus 60 (Uzoh at Figure 7). Uzoh arguably teaches a source 80 to vary the electrochemical current  $i$  (Uzoh at Figure 11a).

The claims include a movement and positioning means for moving and positioning said polishing tool to a target position in a direction facing said polishing object. The specification as originally filed teaches the presence of a Z-axis positioning mechanism 31 for positioning the polishing tool holder 11 to the target position in the Z-axial direction